PCN Number:		20240306004.2					PCN Date:		March 06, 2024			
Title: Adding FFAB as additional wafer probe (EWS) site												
Customer Contact:			Change Management team				Dept:	Quality Services				
Proposed 1 <sup>st</sup> Ship D			ate:	September 02, 2024							ples not orted	
Change Type:												
Assembly Site					Design				Wafer Bump Material			
Assembly Process			5	Data Sheet			Wafer Bump Process					
Assembly Materials			ıls			Part number change				Wafer Fab Site		
Mechanical Specification			n	X	Test Site				Wafer Fab Material			
Packing/Shipping/Labeling				Test Process			Wafer Fab Process					
PCN Details												
Description of Change:												
Texas Ir	strumen	ts Ind	corno	rated I	าลร	gualified FFA	В	as addition	nal	nrohe (	FWS)	site for the

Texas Instruments Incorporated has qualified FFAB as additional probe (EWS) site for the devices listed below to support high volume ramps.

	Current:	New:
Probe Site (EWS)	SFAB (SH-BIP)	FFAB (FR-BIP)

Test coverage, insertions, conditions will remain consistent with current testing.

# **Reason for Change:**

Enable additional probe capacity to support high volume ramps.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

#### **Impact on Environmental Ratings**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	<b>Green Status</b>	IEC 62474
No Change	No Change	No Change	No Change

## Changes to product identification resulting from this PCN:

None

## **Product Affected:**

ATOPA2350UA/2K5	OPA365AQDBVRQ1	REF3125AQDBZRQ1	REF3140AQDBZRQ1
INA333QDGKRQ1	REF3112AQDBZRQ1	REF3130AQDBZRQ1	TMP300BQDCKRQ1
OPA2365AQDRQ1	REF3120AQDBZRQ1	REF3133AQDBZRQ1	

ZVEI ID reference: SEM-TF-01

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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